

TPDxF003 Four-, Six-, and Eight-Channel EMI Filters With Integrated ESD Protection

1 Features

- Four-, Six-, and Eight-Channel EMI Filtering for Data Ports
- –3 dB Bandwidth of 200 MHz
- Greater than 25 dB attenuation at 1 GHz
- IEC 61000-4-2 Level 4 ESD Protection
 - ±12-kV Contact Discharge
 - ±20-kV Air Gap Discharge
- Pi-Style (C-R-C) Filter Configuration (R = 100 Ω, C_{TOTAL} = 17 pF)
- Low 10-nA Leakage Current
- Easy Flow-Through Routing

2 Applications

- Display Interfaces
- Cell Phones
- Tablets
- SVGA Video Connections
- Memory Interfaces

3 Description

The TPDxF003 family is a series of highly integrated devices designed to provide Electromagnetic Interference (EMI) filtering in all systems subjected to electromagnetic interference. These filters also provide a Transient Voltage Suppressor (TVS) diode circuit for Electrostatic Discharge (ESD) protection which prevents damage to the application when subjected to ESD stress far exceeding IEC 61000-4-2 (Level 4).

The TPDxF003 family is specified for –40°C to 85°C operation. These filters are also packaged in space-saving 0.4-mm pitch DQD packages.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|-----------|-------------------|
| TPD4F003 | WSON (8) | 1.70 mm x 1.35 mm |
| TPD6F003 | WSON (12) | 2.50 mm x 1.35 mm |
| TPD8F003 | WSON (16) | 3.30 mm x 1.35 mm |

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Equivalent Schematic

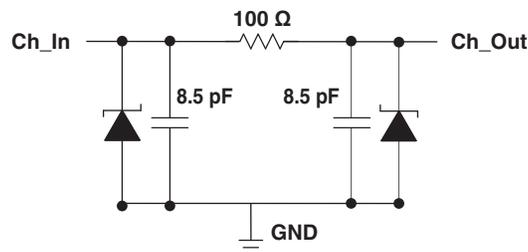


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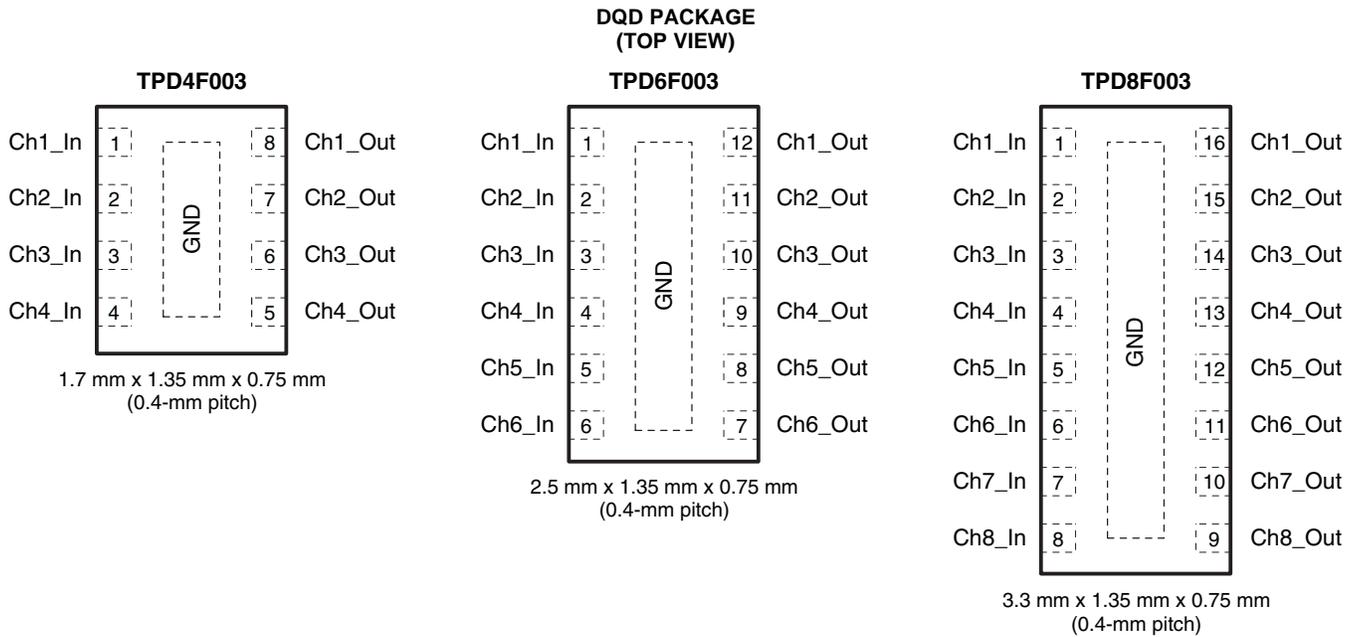
4 Revision History

Changes from Revision D (January 2010) to Revision E

Page

- Added *Handling Rating* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section [1](#)

5 Pin Configuration and Functions



Pin Functions - TPD4F003

| PIN | | I/O | DESCRIPTION |
|---------|------------|-----|---|
| NAME | No. | | |
| ChX_In | 1, 2, 3, 4 | IO | ESD-protected channel, connected to corresponding ChX_Out |
| ChX_Out | 5, 6, 7, 8 | IO | ESD-protected channel, connected to corresponding ChX_In |
| GND | GND | G | Ground |

Pin Functions - TPD6F003

| PIN | | I/O | Description |
|---------|---------------------|-----|---|
| Name | No. | | |
| ChX_In | 1, 2, 3, 4, 5, 6 | IO | ESD-protected channel, connected to corresponding ChX_Out |
| ChX_Out | 7, 8, 9, 10, 11, 12 | IO | ESD-protected channel, connected to corresponding ChX_In |
| GND | GND | G | Ground |

Pin Functions - TPD8F003

| PIN | | I/O | Description |
|---------|-------------------------------|-----|---|
| Name | No. | | |
| ChX_In | 1, 2, 3, 4, 5, 6, 7, 8 | IO | ESD-protected channel, connected to corresponding ChX_Out |
| ChX_Out | 9, 10, 11, 12, 13, 14, 15, 16 | IO | ESD-protected channel, connected to corresponding ChX_In |
| GND | GND | G | Ground |

6 Specifications

6.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT |
|-----------------|----------------------|-----|-----|------|
| V _{IO} | IO to GND | | 6 | V |
| T _J | Junction temperature | | 150 | °C |

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

6.2 Handling Ratings

| | | MIN | MAX | UNIT | |
|--------------------|---------------------------|--|-----|-------|----|
| T _{stg} | Storage temperature range | -65 | 150 | °C | |
| V _(ESD) | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾ | | ±15 | kV |
| | | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾ | | ±1500 | V |
| | | IEC 61000-4-2 ESD Rating - Contact | | ±12 | kV |
| | | IEC 61000-4-2 ESD Rating - Air | | ±20 | |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT |
|-----------------|--|-----|-----|------|
| V _{IO} | | 0 | 5.5 | V |
| T _A | | -40 | 85 | °C |

6.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | TPD4F003 | TPD6F003 | TPD8F003 | UNIT |
|-------------------------------|--|----------|----------|----------|------|
| | | DQD | | | |
| | | 8 PINS | 12 PINS | 16 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 115.6 | 89.2 | 80.8 | °C/W |
| R _{θJC(top)} | Junction-to-case (top) thermal resistance | 108.5 | 100.1 | 88.3 | |
| R _{θJB} | Junction-to-board thermal resistance | 66.4 | 50.5 | 45.8 | |
| ψ _{JT} | Junction-to-top characterization parameter | 6.8 | 9.4 | 9.2 | |
| ψ _{JB} | Junction-to-board characterization parameter | 65.9 | 50.0 | 45.4 | |
| R _{θJC(bot)} | Junction-to-case (bottom) thermal resistance | 33.2 | 31.0 | 31.8 | |

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

T_A = -40°C to 85°C (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT | |
|-----------------|-------------------------|--|--------------------|-----|------|---|
| V _{BR} | DC breakdown voltage | I _{IO} = 10 μA | 6 | | V | |
| R | Resistance | | 85 | 100 | 115 | Ω |
| C | Capacitance (C1 or C2) | V _{IO} = 2.5 V | 8.5 | | pF | |
| I _{IO} | Channel leakage current | V _{IO} = 3.3 V | 10 | | nA | |
| f _C | Cut-off frequency | Z _{SOURCE} = 50 Ω, Z _{LOAD} = 50 Ω | 200 | | MHz | |

- (1) Typical values are at T_A = 25°C.

6.6 Typical Characteristics

6.6.1 IEC Clamping Waveforms (clamp voltage measured both at Ch_Out and Ch_In)

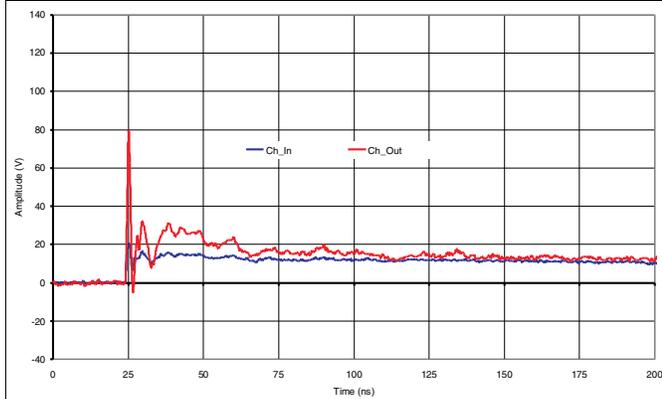


Figure 1. With 8 kV Contact ESD Stress at Ch_Out

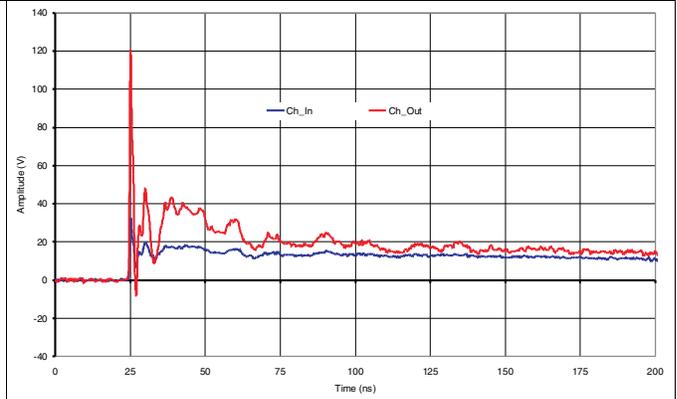


Figure 2. With 12 kV Contact ESD Stress at Ch_Out

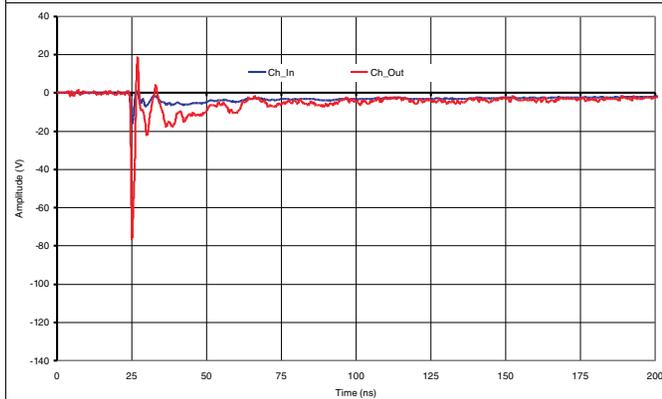


Figure 3. With -8 kV Contact ESD Stress at Ch_Out

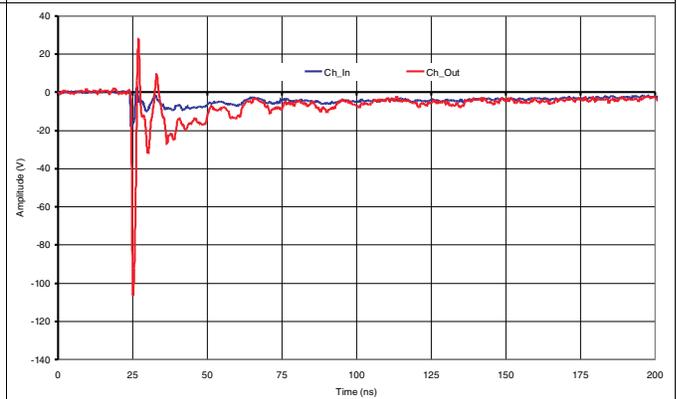


Figure 4. With -12 kV Contact ESD Stress at Ch_Out

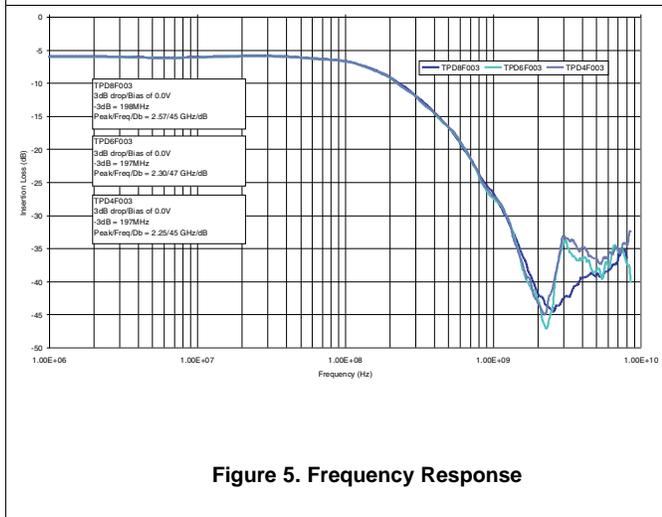


Figure 5. Frequency Response

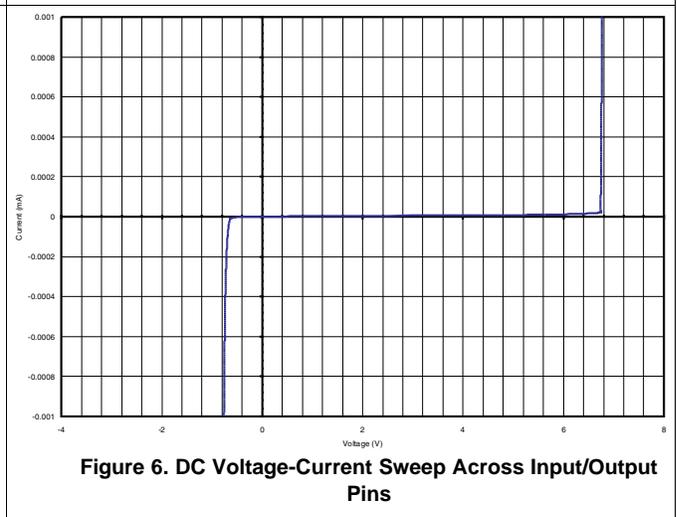


Figure 6. DC Voltage-Current Sweep Across Input/Output Pins

6.6.2 Channel-to-Channel Crosstalk

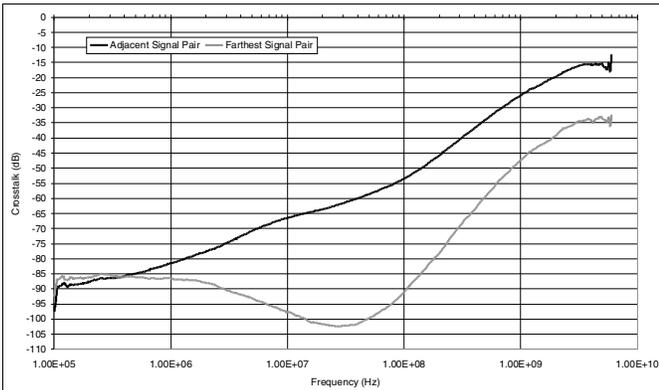


Figure 7. TPD4F003

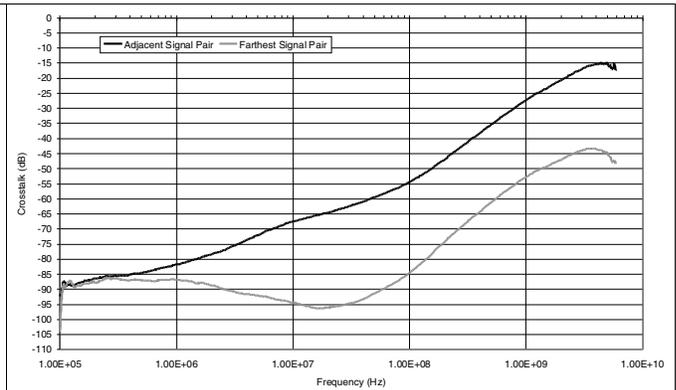


Figure 8. TPD6F003

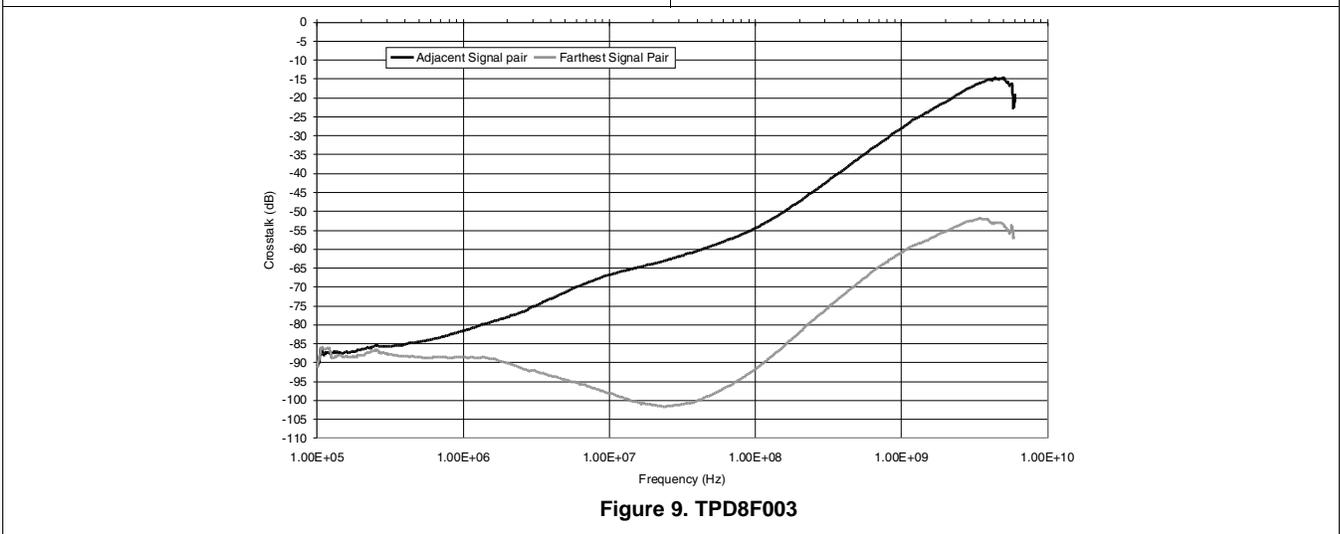


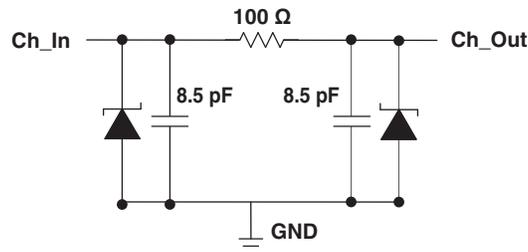
Figure 9. TPD8F003

7 Detailed Description

7.1 Overview

The TPDxF003 family is a series of highly integrated devices designed to provide EMI filtering in all systems subjected to electromagnetic interference. These filters also provide a Transient Voltage Suppressor (TVS) diode circuit for ESD protection which prevents damage to the application when subjected to ESD stress far exceeding IEC 61000-4-2 (Level 4).

7.2 Functional Block Diagram



7.3 Feature Description

The TPDxF003 family is a line of ESD and EMI filtering devices designed to reduce EMI emissions and provide system level ESD protection. Each device can dissipate ESD strikes above the maximum level specified by IEC 61000-4-2 international standard. Additionally, the EMI filtering structure reduces EMI emissions by providing high frequency roll-off.

7.3.1 Four-, Six-, and Eight-Channel EMI Filtering for Data Ports

These devices provide EMI filtering for four, six, or eight channels of data lines.

7.3.2 –3 dB Bandwidth of 200 MHz

These devices have a through –3dB bandwidth of 200 MHz.

7.3.3 Greater Than 25 dB Attenuation at 1 GHz

Signal attenuation is above 25dB at 1 GHz, which provides significant reduction in spurious emissions.

7.3.4 Robust ESD Protection Exceeds IEC 61000-4-2

The ESD protection on all pins exceeds the IEC 61000-4-2 level 4 standard. Contact ESD is rated at ± 12 kV and Air-gap ESD is rated at ± 20 kV.

7.3.5 Pi-Style (C-R-C) Filter Configuration

This family of devices has a pi-style filtering configuration composed of a series resistor and two capacitors in parallel with the I/O pins. The typical resistor value is 100 Ω and the typical capacitor values are 8.5 pF each.

7.3.6 Low 10-nA Leakage Current

The I/O pins feature an ultra-low leakage current of 10-nA (typical) with a bias of 3.3 V.

7.3.7 Easy Flow-Through Routing

The layout of this device makes it easy to add protection to existing layouts. The packages offer flow-through routing which requires minimal changes to existing layout for addition of these devices.

7.4 Device Functional Modes

The TPDxF003 family of devices are passive integrated circuits that passively filter EMI and trigger when voltages are above V_{BR} or below the lower diode voltage (-0.6 V). During ESD events, voltages as high as ± 20 kV (air) can be directed to ground via the internal diode network. Once the voltages on the protected line fall below the trigger levels, the device reverts to passive.

8 Applications and Implementation

8.1 Application Information

The TPDxF003 family are diode type TVS' integrated with series resistors for filtering emitted EMI. As signal passes through the device, higher frequency components are filtered out. This device also provides a path to ground during ESD events and isolates the protected IC. As the current from ESD passes through the TVS, only a small voltage drop is present across the diode. This is the voltage presented to the protected IC. In particular, these filters are ideal for EMI filtering and protecting data lines from ESD at the display, keypad, and memory interfaces.

8.2 Typical Application

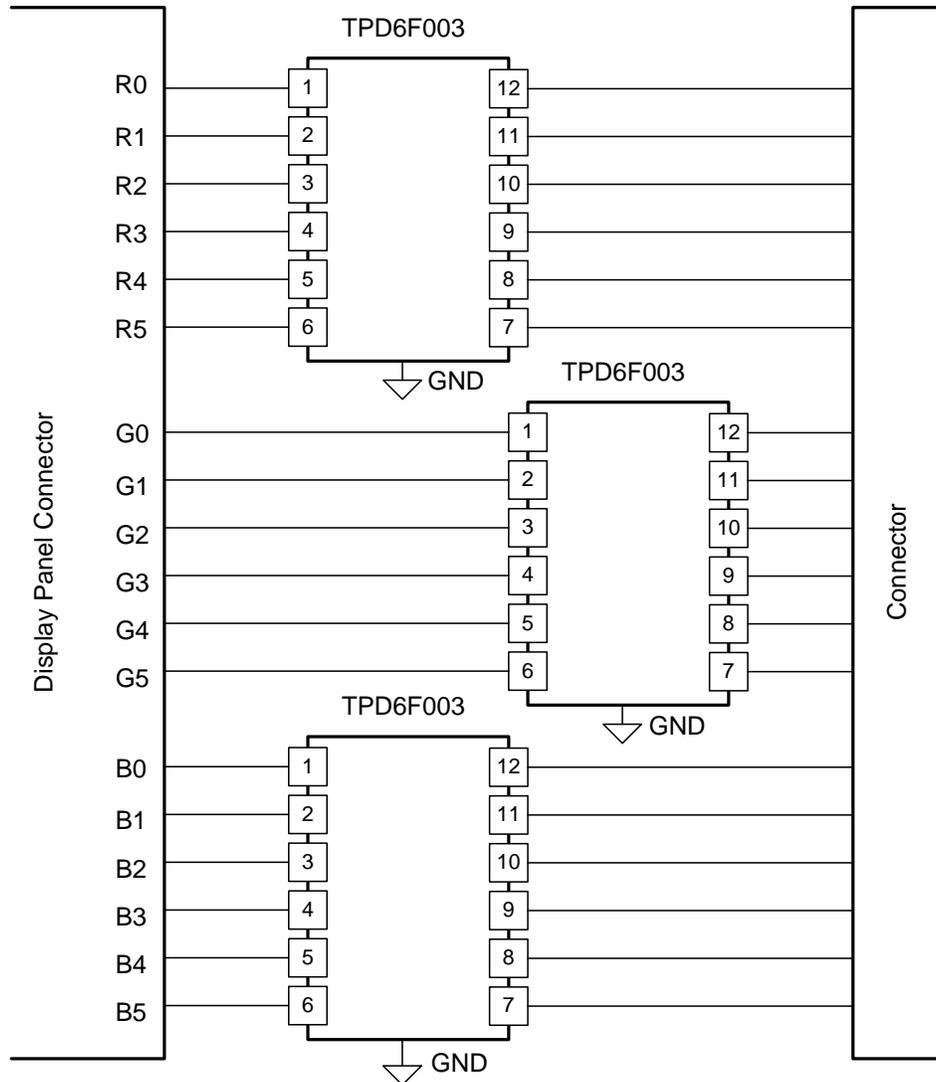


Figure 10. Display Panel Schematic

Typical Application (continued)

8.2.1 Design Requirements

For this design example, three TPD6F003 devices are used in an 18-bit display panel application. This will provide a complete ESD and EMI protection solution for the display connector.

Given the display panel application, the following parameters are known.

| DESIGN PARAMETER | VALUE |
|-------------------------------------|------------|
| Signal range on all pins except GND | 0 V to 5 V |
| Operating Frequency | 100 MHz |

8.2.2 Detailed Design Procedure

To begin the design process, some design parameters must be decided; the designer need to know the following:

- Signal range on all the protected lines
- Operating frequency

8.2.2.1 Signal Range on All Protected Lines

The TPD6F003 has 8 identical protection channels for signal lines. All I/O pins will support a signal range from 0 to 5.5 V.

8.2.2.2 Operating Frequency

The TPD6F003 has a 200 MHz –3dB bandwidth, which supports the operating frequency for this display.

8.2.3 Application Curve

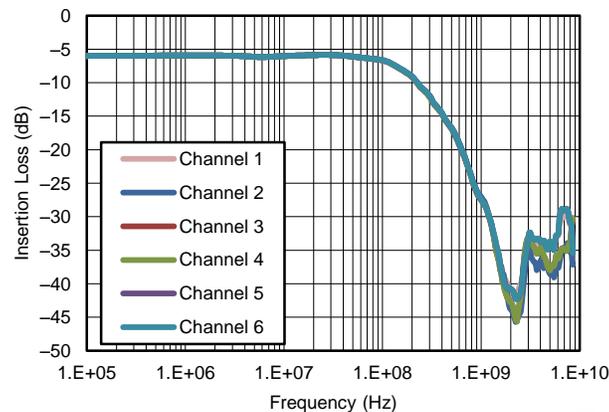


Figure 11. Frequency Response

9 Power Supply Recommendations

This family of devices are passive EMI and ESD devices so there is no need to power them. Care should be taken to not violate the recommended V_{IO} specification (5.5 V) to ensure the device functions properly.

10 Layout

10.1 Layout Guidelines

- The optimum placement is as close to the connector as possible.
 - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
 - The PCB designer needs to minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
 - Electric fields tend to build up on corners, increasing EMI coupling.

10.2 Layout Example

This application is typical of an 18-bit RGB display panel layout.

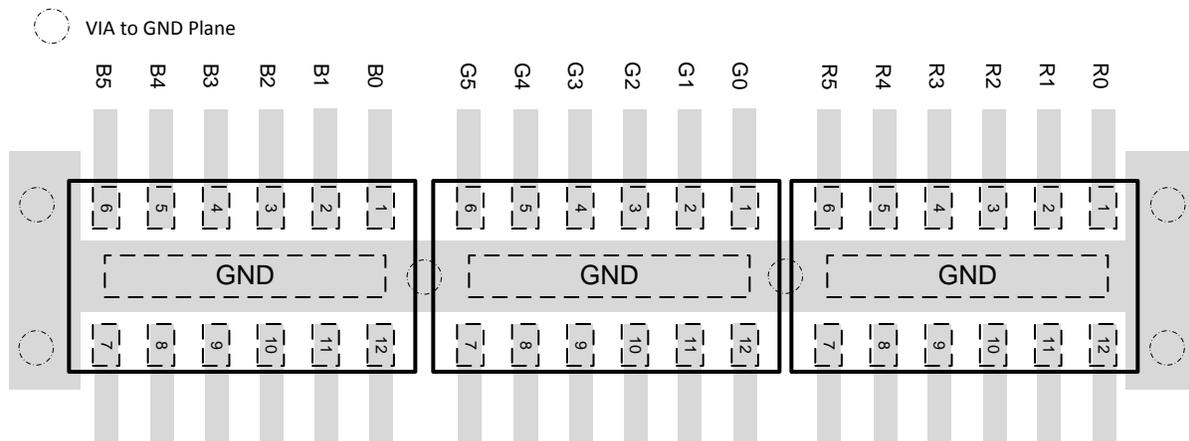


Figure 12. TPD6F003 Layout

11 Device and Documentation Support

11.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 1. Related Links

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|----------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| TPD4F003 | Click here |
| TPD6F003 | Click here |
| TPD8F003 | Click here |

11.2 Trademarks

All trademarks are the property of their respective owners.

11.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| TPD4F003DQDR | ACTIVE | WSON | DQD | 8 | 3000 | RoHS & Green | NIPDAUAG | Level-1-260C-UNLIM | -40 to 85 | 5RS | Samples |
| TPD6F003DQDR | ACTIVE | WSON | DQD | 12 | 3000 | RoHS & Green | NIPDAUAG | Level-1-260C-UNLIM | -40 to 85 | 47S | Samples |
| TPD8F003DQDR | ACTIVE | WSON | DQD | 16 | 3000 | RoHS & Green | NIPDAUAG | Level-1-260C-UNLIM | -40 to 85 | (5US, 5UU) | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPD4F003DQDR | WSON | DQD | 8 | 3000 | 180.0 | 8.4 | 1.65 | 2.0 | 0.95 | 4.0 | 8.0 | Q1 |
| TPD6F003DQDR | WSON | DQD | 12 | 3000 | 180.0 | 8.4 | 1.68 | 2.79 | 0.91 | 4.0 | 8.0 | Q1 |
| TPD8F003DQDR | WSON | DQD | 16 | 3000 | 330.0 | 12.4 | 1.65 | 3.6 | 0.95 | 4.0 | 12.0 | Q1 |

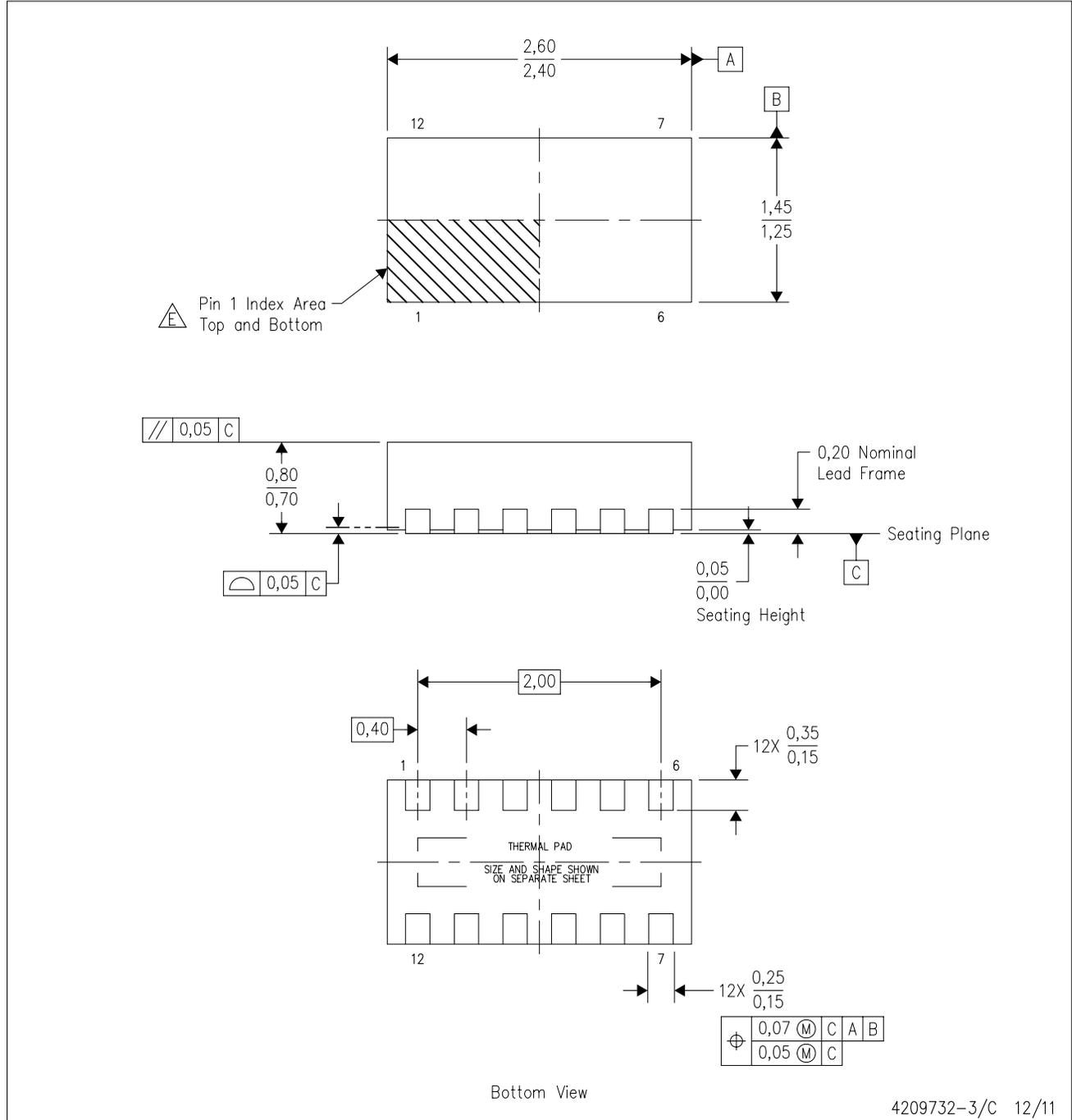
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPD4F003DQDR | WSON | DQD | 8 | 3000 | 183.0 | 183.0 | 20.0 |
| TPD6F003DQDR | WSON | DQD | 12 | 3000 | 183.0 | 183.0 | 20.0 |
| TPD8F003DQDR | WSON | DQD | 16 | 3000 | 358.0 | 335.0 | 35.0 |

DQD (R-PWSON-N12)

PLASTIC SMALL OUTLINE NO-LEAD



4209732-3/C 12/11

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - SON (Small Outline No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- △ Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

THERMAL PAD MECHANICAL DATA

DQD (R-PWSON-N12)

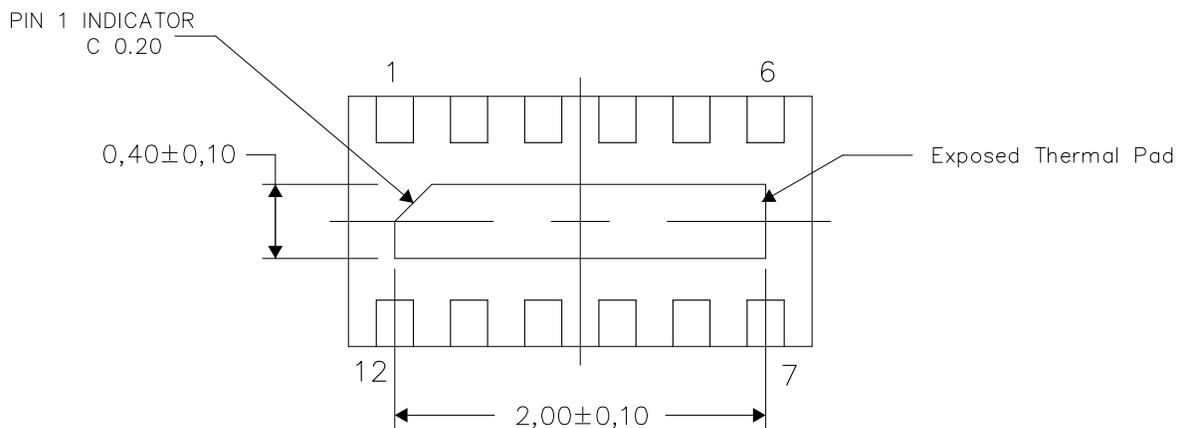
PLASTIC SMALL OUTLINE NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SOIC PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

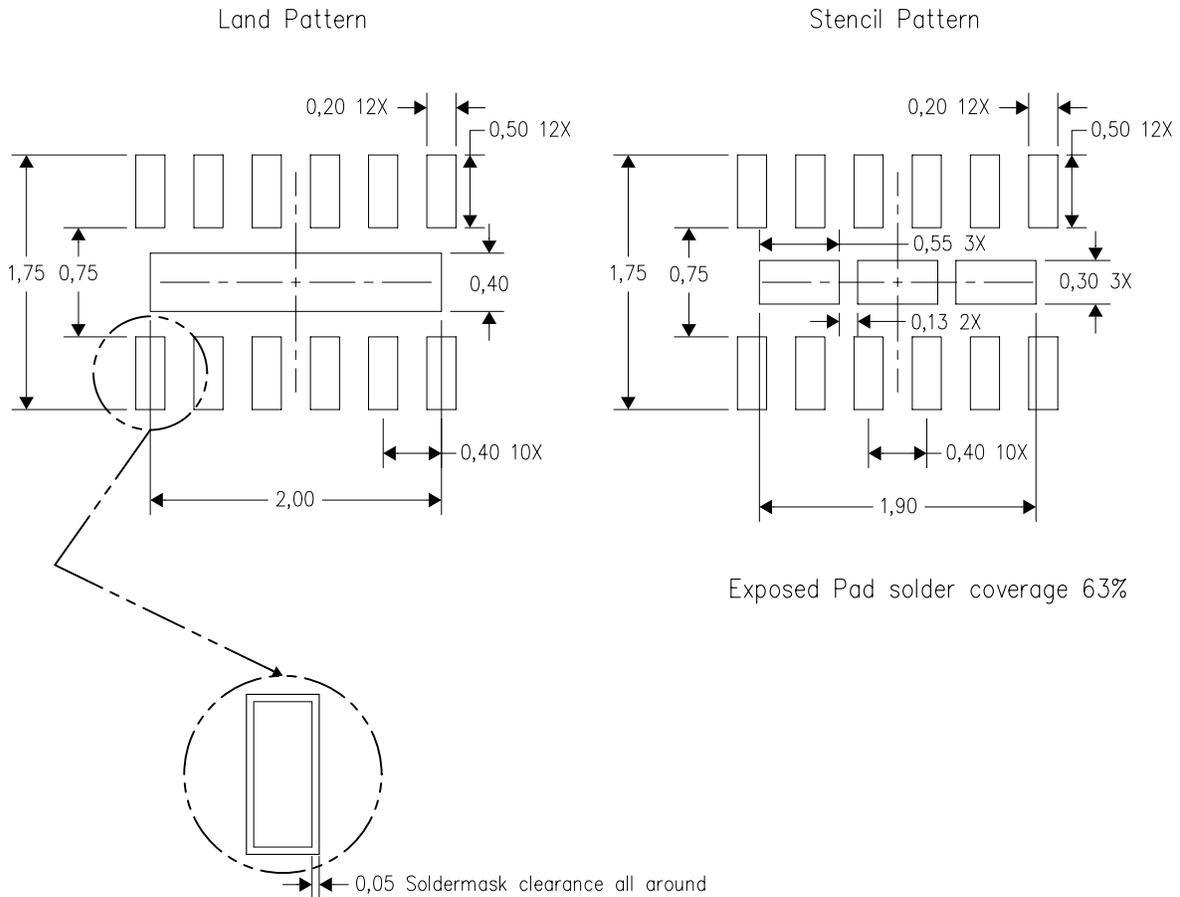


Bottom View

Exposed Thermal Pad Dimensions

4209733-3/C 12/11

NOTE: All linear dimensions are in millimeters

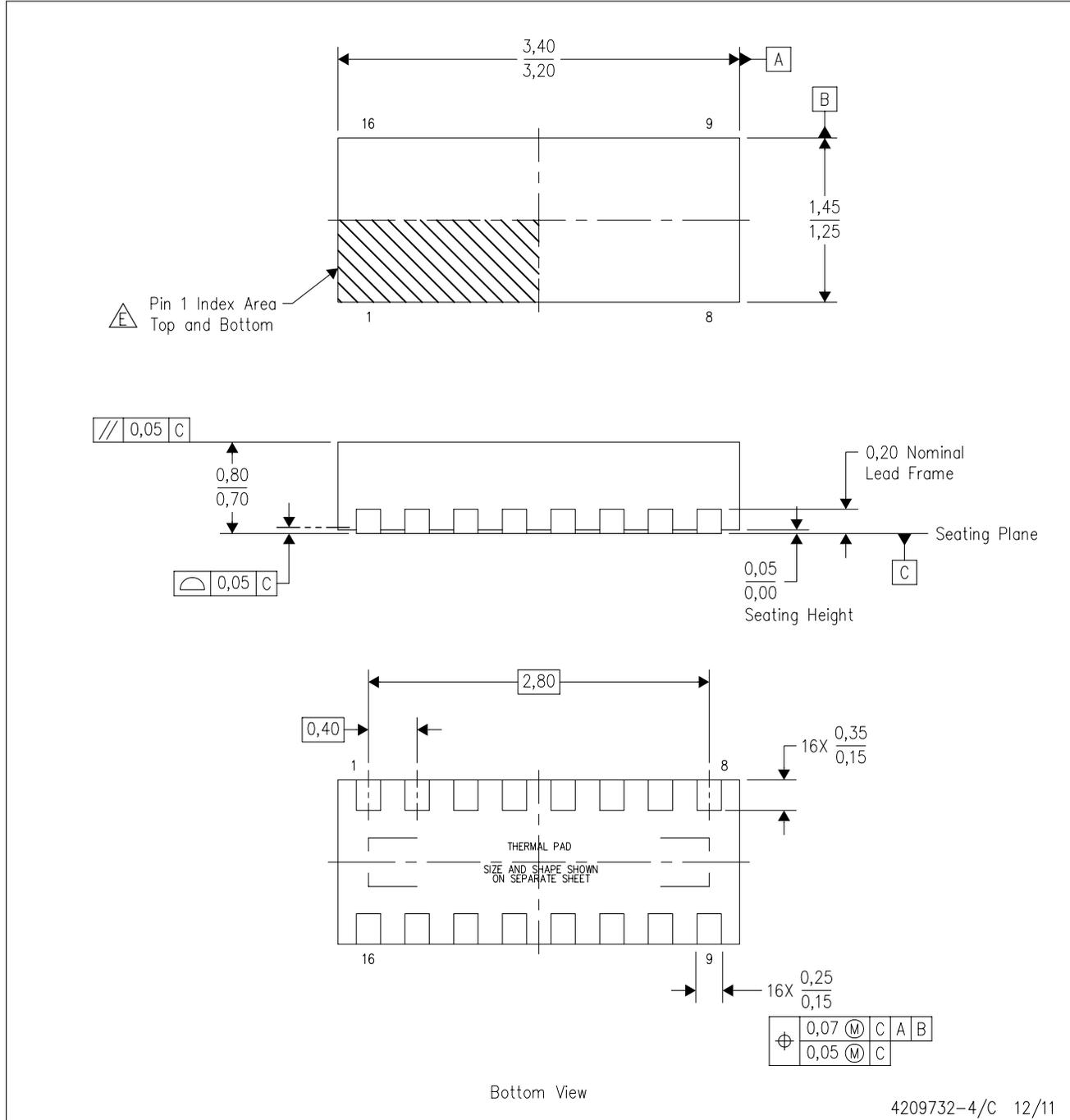


4211174-3/B 01/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

DQD (R-PWSON-N16)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - SON (Small Outline No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- ⚠ Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

THERMAL PAD MECHANICAL DATA

DQD (R-PWSON-N16)

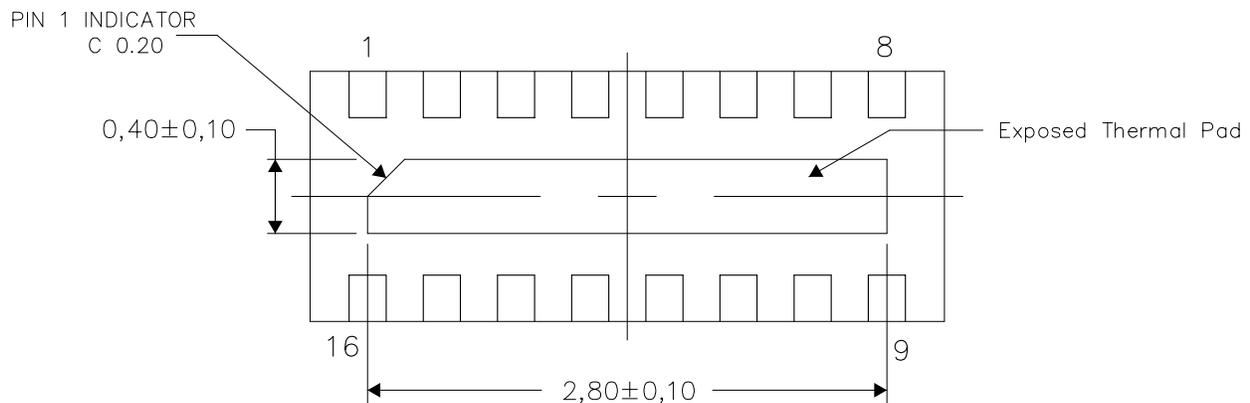
PLASTIC SMALL OUTLINE NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SOIC PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

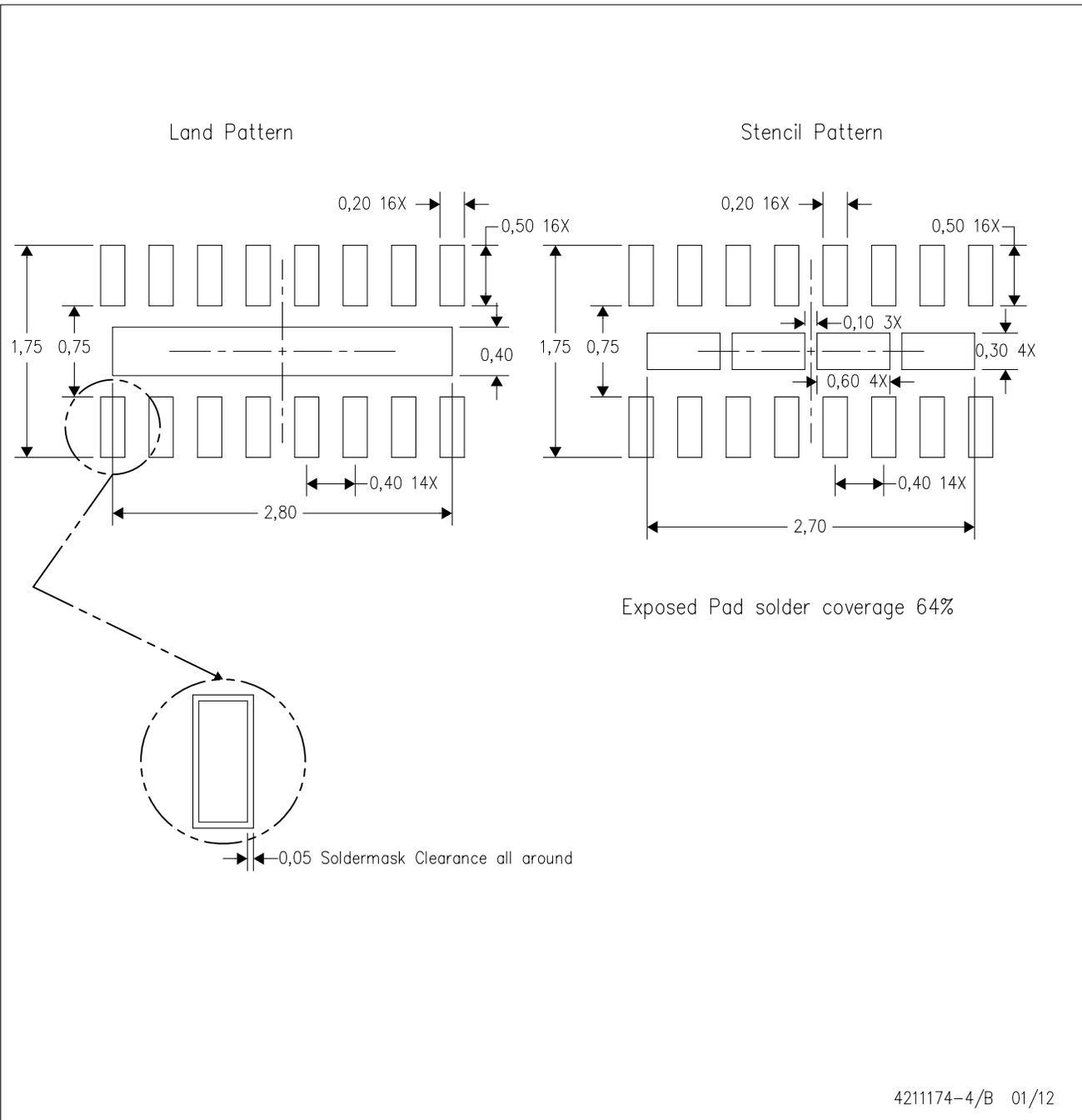


Bottom View

Exposed Thermal Pad Dimensions

4209733-4/C 12/11

NOTE: All linear dimensions are in millimeters

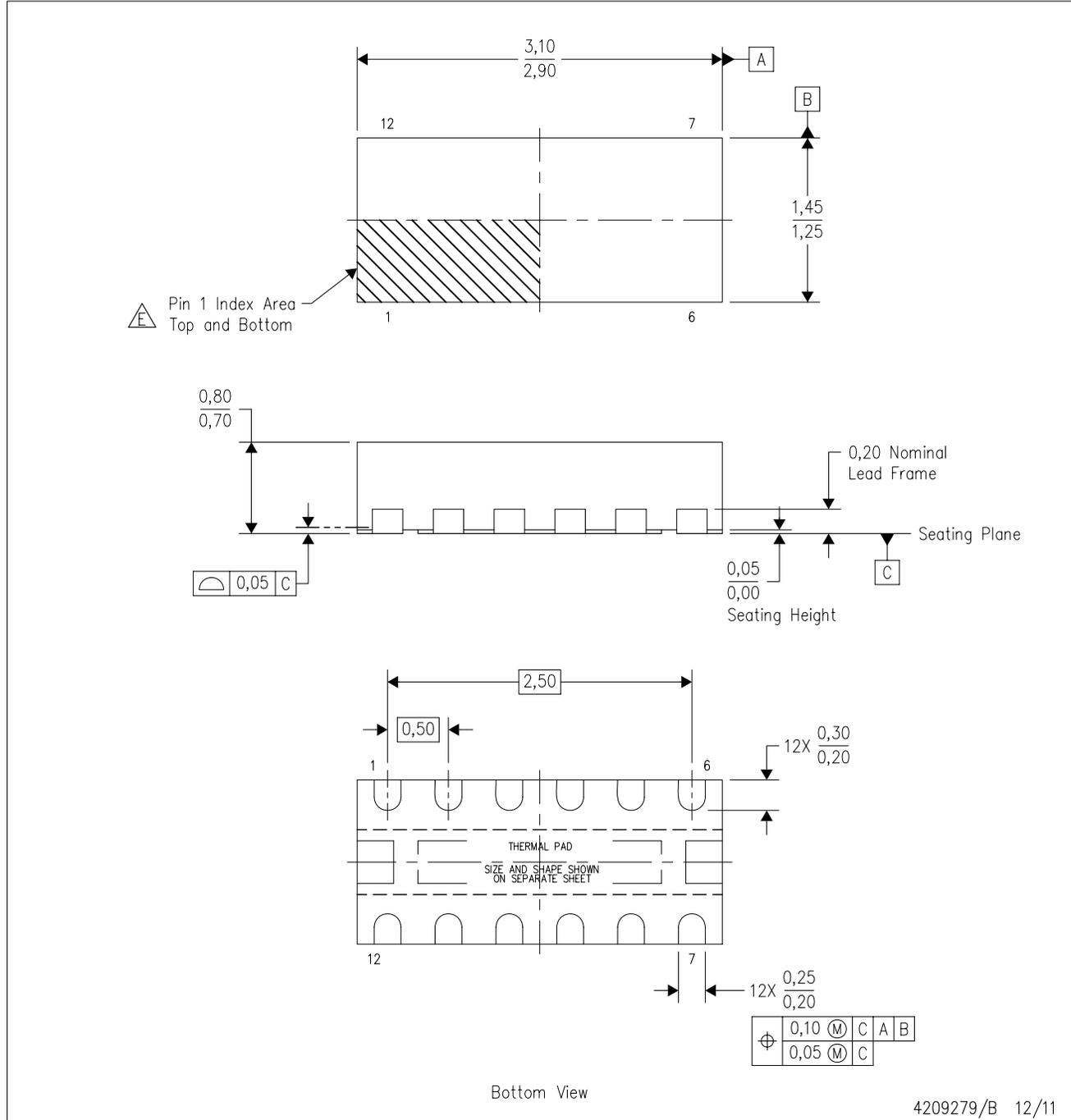


4211174-4/B 01/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

DSV (R-PWSON-N12)

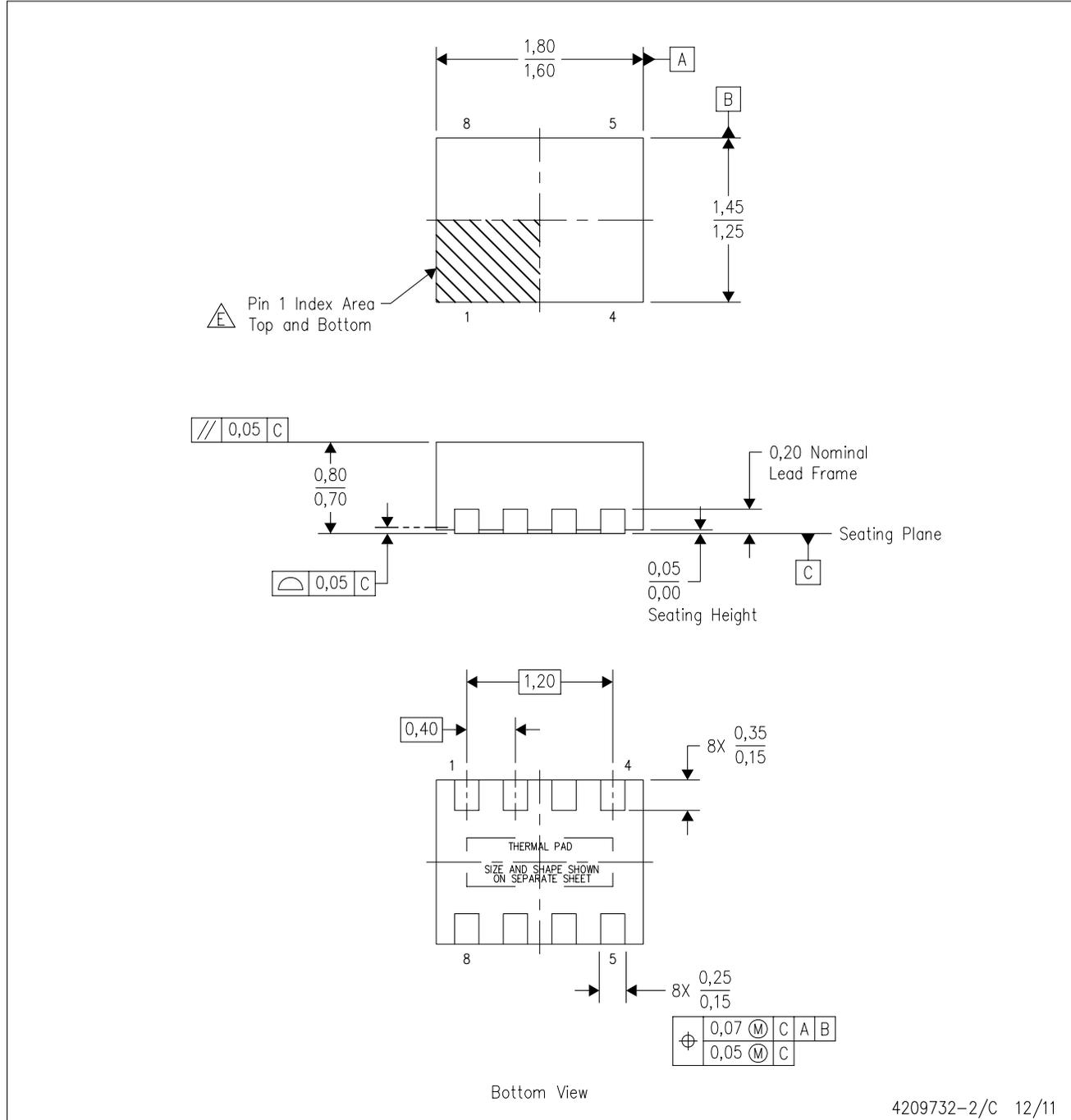
PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - SON (Small Outline No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F** Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

DQD (R-PWSON-N8)

PLASTIC SMALL OUTLINE NO-LEAD



4209732-2/C 12/11

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - SON (Small Outline No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- △ Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

THERMAL PAD MECHANICAL DATA

DQD (R-PWSON-N8)

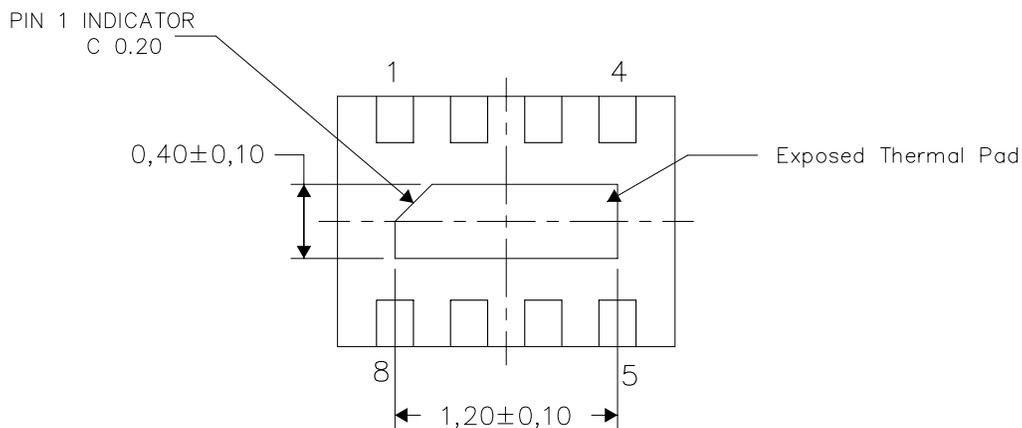
PLASTIC SMALL OUTLINE NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

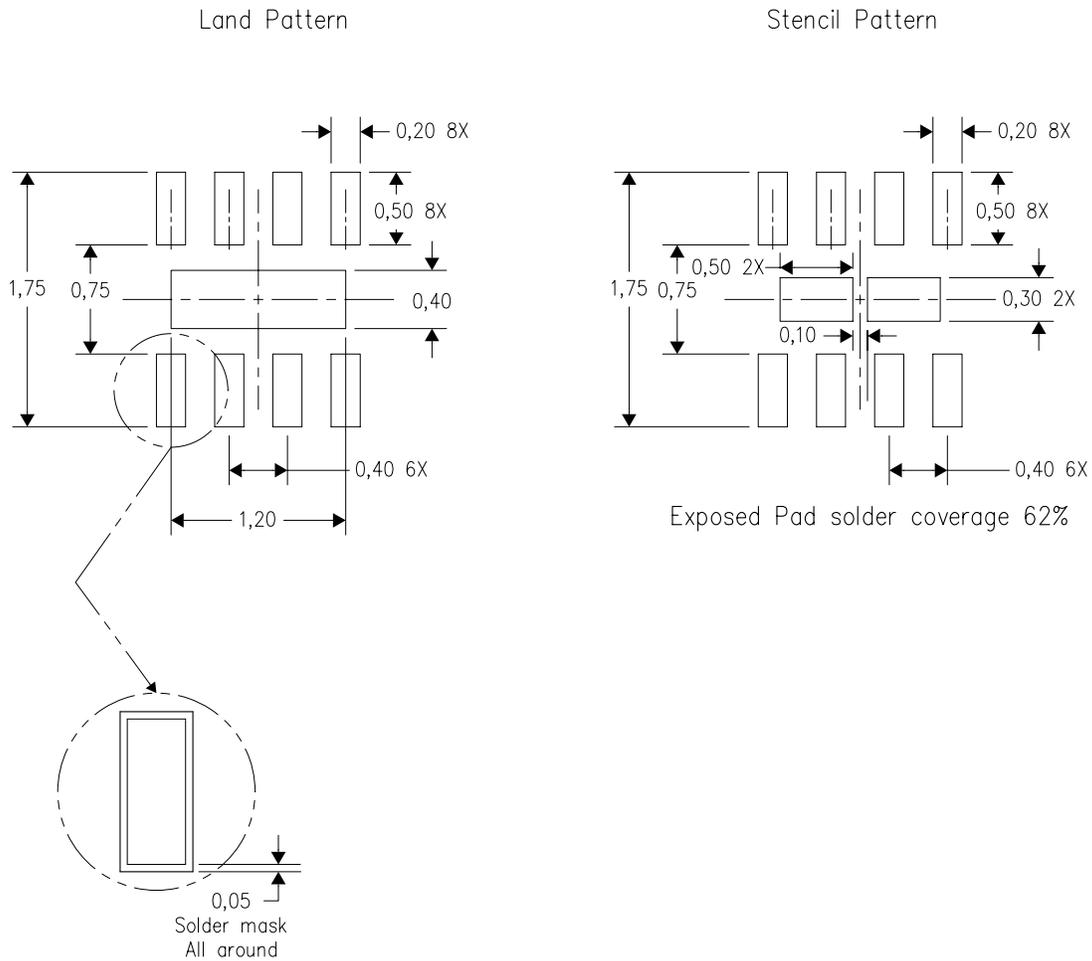


Bottom View

Exposed Thermal Pad Dimensions

4209733-2/C 12/11

NOTE: All linear dimensions are in millimeters



4211174-2/B 01/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
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 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

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